



BGA/CSP DEVELOPMENT UPDATE SERVICE

Fourth Quarter, 2002

The fourth quarterly BGA/CSP update for 2002 features the market forecast for BGAs and CSPs. Growth in the market is analyzed in light of the worldwide economic recession. The CSP forecast includes rigid, flex, and lead frame substrates. The BGA forecast includes ceramic, tape, and plastic packages. Major application areas are described, and a special section is devoted to developments in stacked die (or multichip) packaging including information on packages in production, devices stacked in the packages, and applications. An analysis of trends in DRAM memory packaging is also provided.

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Contents and specifications subject to change without notice. 01/14/03